Thermal Management

1 Part Thermally Conductive RTV Silicone
2 Part Thermally Conductive RTV Silicone
Carbon Conductive Grease
Non - Silicone Heat Transfer
Projection Tube Coolant
Silicone Heat Transfer
Silver Conductive Epoxy
Super Thermal Grease
Thermally Conductive Epoxy

ALL MG PRODUCTS

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3M Engineered Fluids
3M Electronic Liquids
Accessories
Adhesives
Brushes
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Desoldering Braid
Dusters & Circuit Coolers
Electronic Cleaners
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Epoxies
Flux and Flux Remover
Greases & Lubricants
Isopropyl Alcohol
Lead Free Solder
Leaded Solder
Pens
Potting & Encapsulating
Protective Coatings
Prototyping Materials
RTV Silicones
Screen Cleaners
Soldering/desoldering
SpecialtyCleaners
Specialty Products
Swabs
Thermal Management
Thermally Conductive Adhesives
Wipes

Non-Silicone Heat Transfer Compound

RoHS COMPLIANT

8610

BUY NOW

- Special synthetic base, fortified with metal oxides and compounded to a paste -like consistency for ease of application
- High efficient thermal conductive properties
  - Means more rapid transfer of heat for longer component life
- High temperature stability
  - Provides physical properties of low bleed and low evaporation for long -term service in any application that requires Heat Sink Compound.
- Uses synthetic fluids and metal oxide fillers
  - Provides excellent conductive properties that exceed those of other heat sink formulas
- Will not dry, harden, melt or migrate in any heat sink application
- Compatible with metal and plastic components
- Also available in a silicone version

Benefits of Non Silicone Heat Transfer Compound OVER Silicone

No migration and component contamination.

Applications

- Typically, Heat Transfer Compounds (heat sink compounds) are used in OEM Electronic Component Plants to insure fast, accurate heat transfer in electronic components and circuitry
- Other used:
  - Semiconductor Mounting Devices
  - Thermal joints
  - Ballast heat transfer mediums
  - Power resistor mountings
  - Thermocouple wells
  - Transistor diodes & silicone rectifier base and mounting studs
  - ALL electric and electronic devices where efficient heat transfer cooling through thermal coupling is required

MSDS

Specs

Sizes

Info on dispensing equipment (Cammda)

View an animated demonstration of how to apply Silicone Heat Transfer Compound

View an animated demonstration of how to apply Silicone Heat Transfer Compound

Specifications

Physical Properties	Test Method	Non Silicone 8610	Silicone 860
Appearance	Visual	Off white / smooth paste	White paste
Consistency	ASTM D 217	310 - 320	
Specific Gravity @ 25°C (77°F)		2.5 min	2.3 min
Bleed % 24 hours @ 200°C	FTM - 321	1.0% max	2.0% max
Evaporation 24 hours @ 200°C	FTM - 321	2.0% max	2.0% max
Dropping Point	ASTM D - 566	> 500°F (260°C)	> 500°F (260°C)
Min. operating temp.		- 40°F/ - 40°F	55°F/48°C
Max. operating temp.		200°C	200°C (consistent) 300°C (intermittent)
Electrical Properties	**Test Method**	**Non Silicone 8610**	**Silicone 860**
Thermal Conductivity	Hot Wire Method Heat Flow #36 °C	in W/m·K (BTU in /(hr ft ^{2} F)) 0.773 (5.36)	in W/m·K (BTU in /(hr ft ^{2} F)) 0.657 (4.56)
Dielectric Strength (0.05l gap)	ASTM D - 149	350 V/MIL	400 V/MIL
Dielectric Constant @ 1000 Hz	ASTM D - 150	4.4	3.81
Dissipation Factor @ 1000 Hz	ASTM D 150	0.0021	0.0032
Resistivity @ 21°C	ASTM D 150	6.38 x 10 ^{13} Ohm • cm	1.5 x 10 ^{15} Ohm • cm

Available Sizes

Catalog Number	Sizes Available	Description
8610 - 60G	60g (2 oz)	Liquid - TUBE
8610 - 1P	1 pint (2.5 lbs)	Tub

Google Search MG